

## AMENDMENTS TO THE CLAIMS

Claims 1-8 have been previously canceled without prejudice.

Claims 11-15 have been previously withdrawn by the Examiner as being drawn to a different statutory invention. Please cancel claims 11-15 without prejudice.

Please amend claim 9.

Please renumber claims 27-29 as 26-28. Please see an explanation provided under the Remarks section.

This listing of the claims replaces all prior versions, and listings, of claims in the application:

### Listing of the Claims

1. – 8. (Canceled)

9. (Currently Amended) An apparatus comprising:

a platen;

a polishing pad; ~~said polishing pad~~ disposed over [a] said platen;

a segmented cathode disposed between said platen and said polishing pad;

a slurry disposed on said polishing pad;

a wafer disposed on said polishing pad and said slurry; ~~said wafer mounted in~~

a wafer carrier to hold said wafer;

a segmented anode disposed between said wafer and said wafer carrier;  
a power supply to apply a voltage between said segmented cathode  
~~polishing pad~~ and said segmented anode ~~wafer~~; and  
a computer, ~~said computer~~ to vary said voltage ~~during operation of said~~  
~~apparatus~~.

10. (Previously Presented) The apparatus of claim 9 wherein said wafer comprises a continuous and conductive surface layer.

11. – 15. (Canceled)

16. (Previously Presented) The apparatus of claim 9 wherein said computer optimizes polishing rates for different materials on said wafer by varying said voltage.

17. (Previously Presented) The apparatus of claim 9 wherein said computer varies said voltage as a function of time.

18. (Previously Presented) The apparatus of claim 9 wherein said computer varies said voltage as a function of temperature.

19. (Previously Presented) The apparatus of claim 9 wherein said computer varies said voltage as a function of process parameter.

20. (Previously Presented) The apparatus of claim 19 wherein said process parameter comprises slurry flowrate.

21. (Previously Presented) The apparatus of claim 9 wherein said computer varies said voltage as a function of tool parameter.

22. (Previously Presented) The apparatus of claim 21 wherein said tool parameter comprises speed of rotation of said platen.

23. (Previously Presented) The apparatus of claim 21 wherein said tool parameter comprises speed of rotation of said wafer carrier.

24. (Previously Presented) The apparatus of claim 9 wherein said computer comprises feedforward control of an electrochemical process.

25. (Previously Presented) The apparatus of claim 9 wherein said computer comprises feedback control of an electrochemical process.

26. (Renumbered After Being Previously Presented) The apparatus of claim 9 wherein said computer comprises proportional control of said voltage.

27. (Renumbered After Being Previously Presented) The apparatus of claim 9 wherein said computer comprises differential control of said voltage.

28. (Renumbered After being Previously Presented) The apparatus of claim 9 wherein said computer comprises integral control of said voltage.